

# CALL FOR PARTICIPATION



9th IEEE WORKSHOP ON

## SIGNAL PROPAGATION ON INTERCONNECTS

Sponsored by the IEEE Computer Society – Test Technology Technical Council (TTTC)  
and by the IEEE Components, Packaging, and Manufacturing Technology (CPMT) Society  
**May 10-13, 2005 · “Dorint Sporthotel” · Garmisch-Partenkirchen, Germany**

During the last eight years, the IEEE Workshop on Signal Propagation on Interconnects has been developed into a forum of exchange on the latest research results in this area. The aim of this ensuing workshop is to report on the most recent developments in the field of interconnect modeling, simulation and measurement on chips, boards, and packages. The event is also meant to bring together developers and researchers from industry and academia in order to encourage cooperation. In view of the last years' success, the committee is looking forward to the 9th IEEE Workshop on Signal Propagation on Interconnects where world class developers and researchers will share and discuss leading-edge results in the famous and beautiful city of Garmisch-Partenkirchen, Germany. The social events bundle takes care you'll never forget where you learned the latest and hottest news about interconnects and testing: we are going to have a guided tour to a friary and an bavarian evening. The workshop will be held in English. Detailed information about the workshop and its location are available on the website <http://www.spi.uni-hannover.de>. We are all looking forward to see you in Garmisch-Partenkirchen.

### Main topics of the workshop will include, but are not limited to:

- Frequency Domain Measurement Techniques
- Time Domain Measurement Techniques
- Modeling Techniques of Package & On-Chip Interconnects
- Macro-Modeling
- Simulation Techniques for Interconnect Structures
- Electromagnetic Field Theory
- Analysis and Modeling of Power Distribution Networks
- Propagation Characteristics on Transmission Lines
- Coupling Effects on Interconnects
- Substrate Effects
- Guided Waves on Interconnects
- Radiation & Interference
- Electromagnetic Compatibility
- Power/Ground-Noise
- Testing & Interconnects
- Optical Interconnects

### Workshop Standing Committee:

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Advance Program and Additional Information: <http://www.spi.uni-hannover.de>